

# PCMFxUSB3B/C series

Common-mode EMI filter for differential channels with integrated bidirectional ESD protection

Rev. 2 — 29 January 2019

Product data sheet

## 1. General description

Common-mode ElectroMagnetic Interference (EMI) filters with integrated bidirectional ElectroStatic Discharge (ESD) protection for one, two and three differential channels. The devices are designed to provide low insertion loss for differential high-speed signals on each channel while unwanted common-mode signals are attenuated.

Each differential channel incorporates two signal lines that are coupled by integrated coils. Diodes provide protection to downstream components from ESD voltages up to  $\pm 20$  kV on each signal line.

**Table 1. Product overview**

| Type number  | Number of channels | Package Name |
|--------------|--------------------|--------------|
| PCMF1USB3B/C | 1                  | WLCSP5       |
| PCMF2USB3B/C | 2                  | WLCSP10      |
| PCMF3USB3B/C | 3                  | WLCSP15      |

## 2. Features and benefits

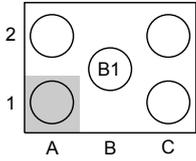
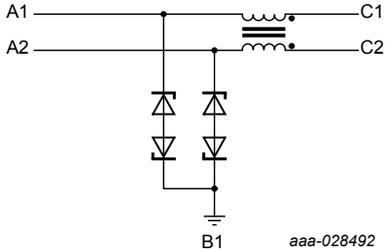
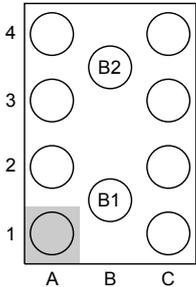
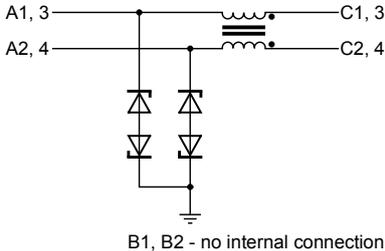
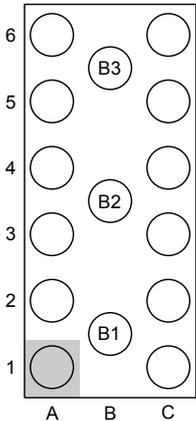
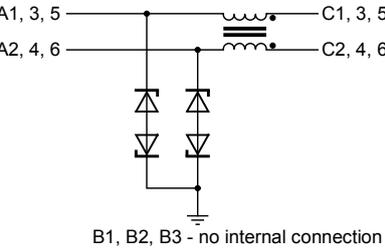
- One, two and three differential channels common-mode EMI filters with integrated ESD protection
- ESD protection up to  $\pm 20$  kV contact discharge according to IEC 61000-4-2
- Superior common-mode suppression over a wide frequency range
- Superior RF performance compared to other integrated filters or discrete filters with external ESD protection
- Extremely high symmetry between line pairs
- Industry-standard Wafer-Level Chip-Scale Packages: WLCSP5, 10 and 15 for smaller footprint

## 3. Applications

- Smartphone, cellular and cordless phone
- USB 3.2, USB 2.0, HDMI 2.0, HDMI 1.4
- General-purpose downstream ESD protection for differential data lines
- Tablet PC and Mobile Internet Device (MID)
- MIPI M-PHY and D-PHY as used in Camera Serial Interface (CSI) and Display Serial Interface (DSI)

### 4. Pinning information

Table 2. Pinning

| Pin                                 | Symbol   | Description          | Simplified outline   | Graphic symbol   |
|-------------------------------------|----------|----------------------|--|--|
| <b>PCMF1USB3B/C (WLCSP5_2-1-2)</b>  |          |                      |  |  |
| A1                                  | CH1_IN+  | channel 1+, external |  <p>Transparent top view<br/><b>WLCSP5_2-1-2</b></p>    |  <p>aaa-028492</p>   |
| A2                                  | CH1_IN-  | channel 1-, external |  |  |
| B1                                  | GND_CH1  | ground channel 1     |  |  |
| C1                                  | CH1_OUT+ | channel 1+, internal |  |  |
| C2                                  | CH1_OUT- | channel 1-, internal |  |  |
| <b>PCMF2USB3B/C (WLCSP10_4-2-4)</b> |          |                      |  |  |
| A1                                  | CH1_IN+  | channel 1+, external |  <p>Transparent top view<br/><b>WLCSP10_4-2-4</b></p>  |  <p>B1, B2 - no internal connection<br/>aaa-028493</p>       |
| A2                                  | CH1_IN-  | channel 1-, external |  |  |
| A3                                  | CH2_IN+  | channel 2+, external |  |  |
| A4                                  | CH2_IN-  | channel 2-, external |  |  |
| B1                                  | GND_CH1  | ground channel 1     |  |  |
| B2                                  | GND_CH2  | ground channel 2     |  |  |
| C1                                  | CH1_OUT+ | channel 1+, internal |  |  |
| C2                                  | CH1_OUT- | channel 1-, internal |  |  |
| C3                                  | CH2_OUT+ | channel 2+, internal |  |  |
| C4                                  | CH2_OUT- | channel 2-, internal |  |  |
| <b>PCMF3USB3B/C (WLCSP15_6-3-6)</b> |          |                      |  |  |
| A1                                  | CH1_IN+  | channel 1+, external |  <p>Transparent top view<br/><b>WLCSP15_6-3-6</b></p> |  <p>B1, B2, B3 - no internal connection<br/>aaa-028494</p> |
| A2                                  | CH1_IN-  | channel 1-, external |  |  |
| A3                                  | CH2_IN+  | channel 2+, external |  |  |
| A4                                  | CH2_IN-  | channel 2-, external |  |  |
| A5                                  | CH3_IN+  | channel 3+, external |  |  |
| A6                                  | CH3_IN-  | channel 3-, external |  |  |
| B1                                  | GND_CH1  | ground channel 1     |  |  |
| B2                                  | GND_CH2  | ground channel 2     |  |  |
| B3                                  | GND_CH3  | ground channel 3     |  |  |
| C1                                  | CH1_OUT+ | channel 1+, internal |  |  |
| C2                                  | CH1_OUT- | channel 1-, internal |  |  |
| C3                                  | CH2_OUT+ | channel 2+, internal |  |  |
| C4                                  | CH2_OUT- | channel 2-, internal |  |  |
| C5                                  | CH3_OUT+ | channel 3+, internal |  |  |
| C6                                  | CH3_OUT- | channel 3-, internal |  |  |

## 5. Ordering information

Table 3. Ordering information

| Type number  | Package |   |
|--------------|---------|---|
|              | Name    | Description                                     |
| PCMF1USB3B/C | WLCSP5  | wafer level chip-size package; 5 bumps (2-1-2)  |
| PCMF2USB3B/C | WLCSP10 | wafer level chip-size package; 10 bumps (4-2-4) |
| PCMF3USB3B/C | WLCSP15 | wafer level chip-size package; 15 bumps (6-3-6) |

## 6. Marking

Table 4. Marking codes

| Type number  | Marking code |
|--------------|--------------|
| PCMF1USB3B/C | PF1B         |
| PCMF2USB3B/C | PF2B         |
| PCMF3USB3B/C | PF3B         |

## 7. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol    | Parameter                       | Conditions  | Min  | Max  | Unit |
|-----------|---------------------------------|---|------|------|------|
| $V_I$     | input voltage                   |   | -4   | 4    | V    |
| $V_{ESD}$ | electrostatic discharge voltage | IEC 61000-4-2, level 4; all input pins to ground  |      |      |      |
|           |                                 | • contact discharge                               | -20  | 20   | kV   |
|           |                                 | • air discharge                                   | -20  | 20   | kV   |
|           |                                 | IEC 61000-4-2, level 4; all output pins to ground |      |      |      |
|           |                                 | • contact discharge                               | -2   | 2    | kV   |
|           |                                 | • air discharge                                   | -2   | 2    | kV   |
| $I_{PPM}$ | rated peak-pulse current        | $t_p = 8/20 \mu s$                                | -9.5 | 9.5  | A    |
| $T_{stg}$ | storage temperature             |   | -40  | +125 | °C   |
| $T_{amb}$ | ambient temperature             |   | -40  | +125 | °C   |

## 8. Characteristics

### 8.1. Channel characteristics

**Table 6. Channel characteristics**

$T_{amb} = 25\text{ °C}$  unless otherwise specified.

| Symbol      | parameter                 | Conditions                                |     | Min | Typ  | Max | Unit     |
|-------------|---------------------------|---|-----|-----|------|-----|----------|
| $R_{S(ch)}$ | channel series resistance | single line; input to output              | -   | -   | 2.6  | -   | $\Omega$ |
| $C_d$       | diode capacitance         | $f = 1\text{ MHz}$ ; $V_I = 2.5\text{ V}$ | [1] | -   | 0.3  | -   | pF       |
| $I_{RM}$    | reverse leakage current   | per line; $V_I = 4\text{ V}$              |     | -   | 1    | 100 | nA       |
| $V_{BR}$    | breakdown voltage         | $I_R = 1\text{ mA}$                       |     | 6   | 9    | -   | V        |
| $R_{dyn}$   | dynamic resistance        | TLP; positive transient                   | [2] | -   | 0.22 | -   | $\Omega$ |
|             |                           | TLP; negative transient                   | [2] | -   | 0.22 | -   | $\Omega$ |

[1] This parameter is guaranteed by design

[2] 100 ns Transmission Line Pulse (TLP); 50  $\Omega$ ; pulser at 70 ns to 90 ns.

### 8.2. Frequency characteristics

**Table 7. Frequency characteristics**

$T_{amb} = 25\text{ °C}$  unless otherwise specified.

| Symbol  | Parameter         | Conditions |     | Min | Typ | Max | Unit |
|---|-------------------|------------|-----|-----|-----|-----|------|
| <b>Differential mode: <math>S_{dd21}</math></b> |                   |            |     |     |     |     |      |
| $f_{-3dB}$                                      | cut-off frequency |            | [1] | -   | 8.1 | -   | GHz  |

[1] Normalized to attenuation at 1 MHz.

Common-mode EMI filter for differential channels with integrated bidirectional ESD protection

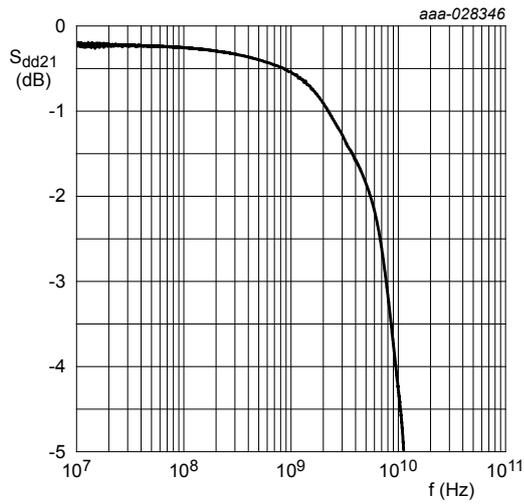


Fig. 1. Differential mode insertion loss; typical values

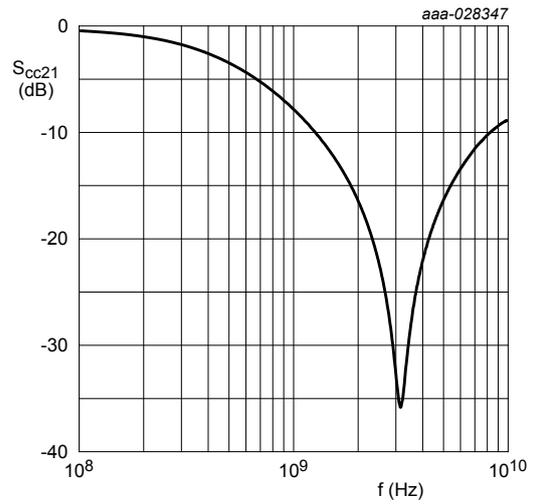
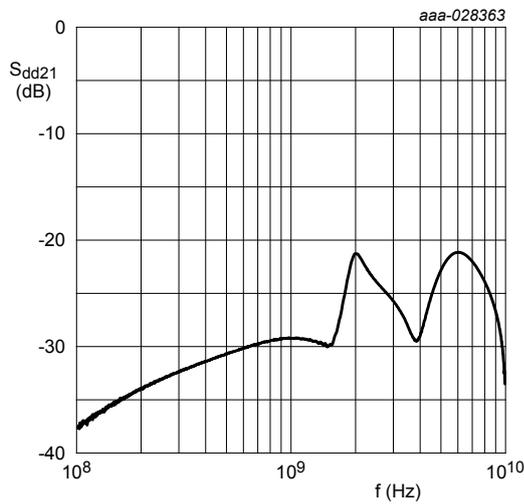
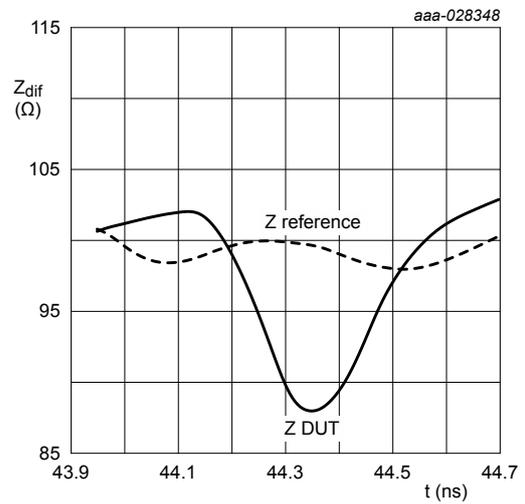


Fig. 2. Common-mode insertion loss; typical values



CH1 to CH2

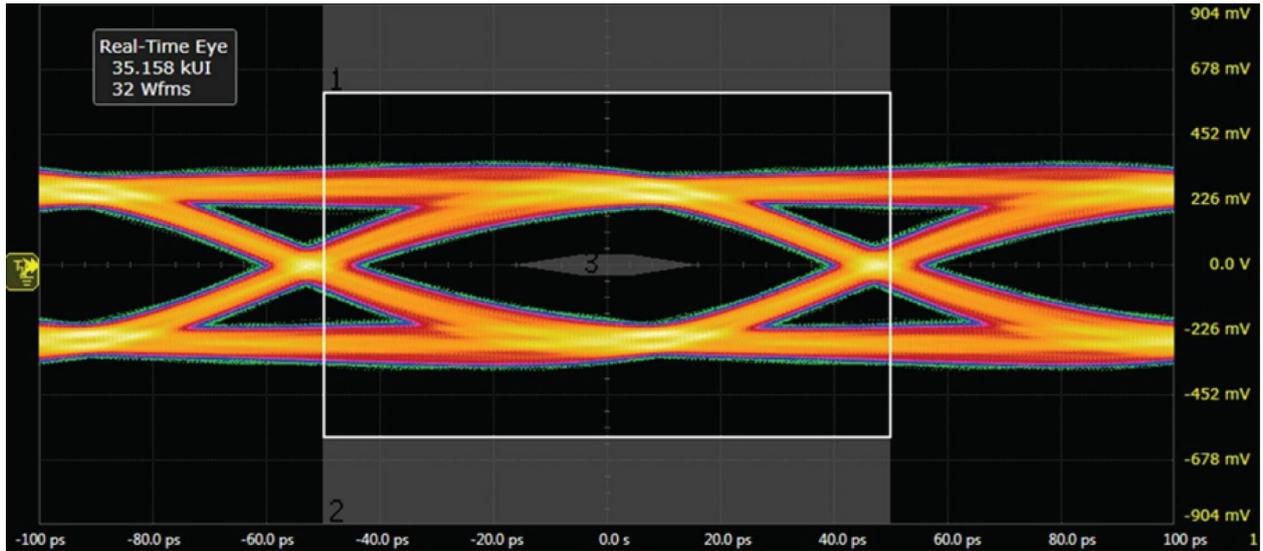
Fig. 3. Differential crosstalk; typical values



$t_r = 200$  ps

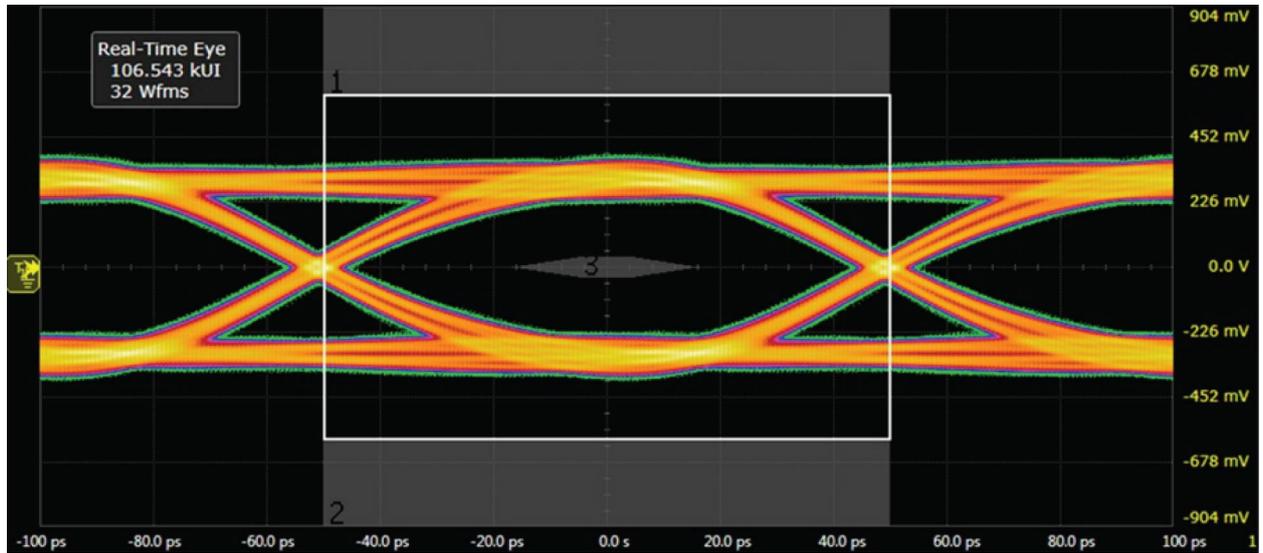
Fig. 4. Differential Time Domain Reflectometer (TDR) plot; typical values

Common-mode EMI filter for differential channels with integrated bidirectional ESD protection



aaa-028349

Fig. 5. USB 3.2 eye diagram 10 Gbps, test board with PCMFxUSB3B/C; typical values



aaa-028350

Fig. 6. USB 3.2 eye diagram 10 Gbps, test board without device; typical values

Common-mode EMI filter for differential channels with integrated bidirectional ESD protection

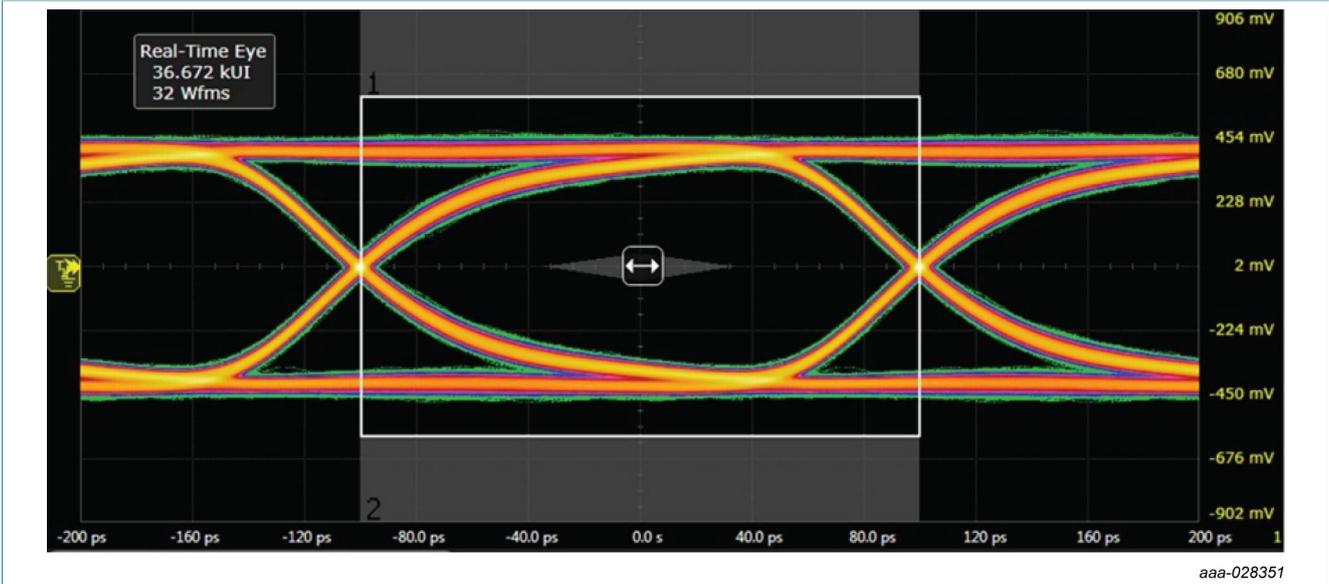


Fig. 7. USB 3.2 eye diagram 5 Gbps, test board with PCMFxUSB3B/C; typical values

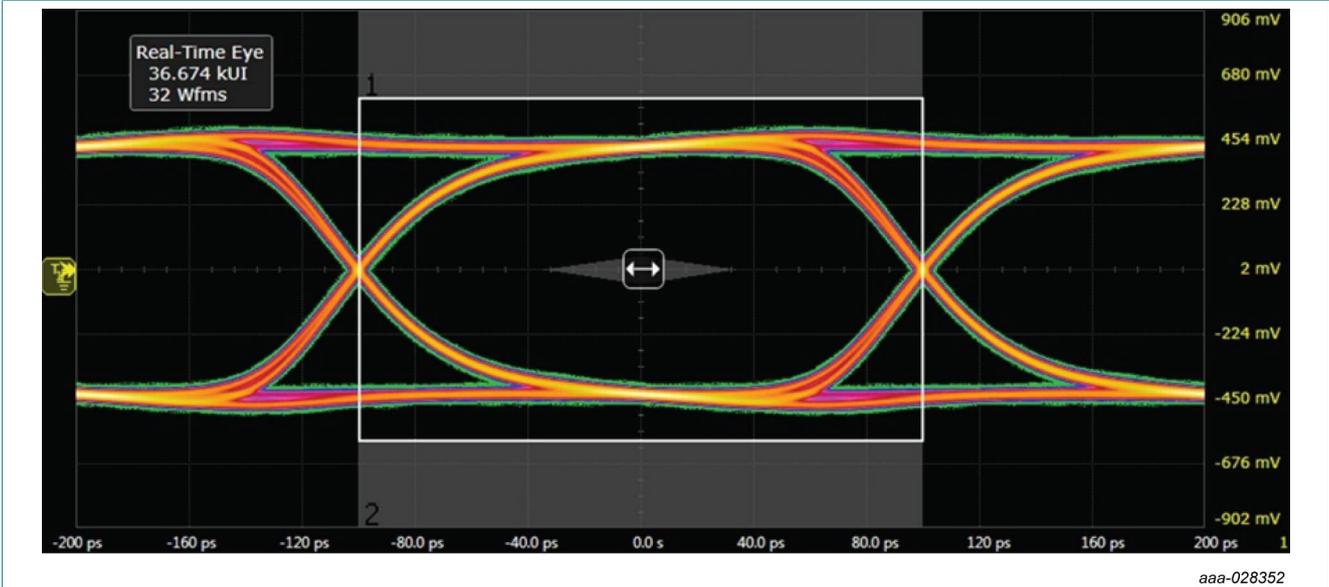
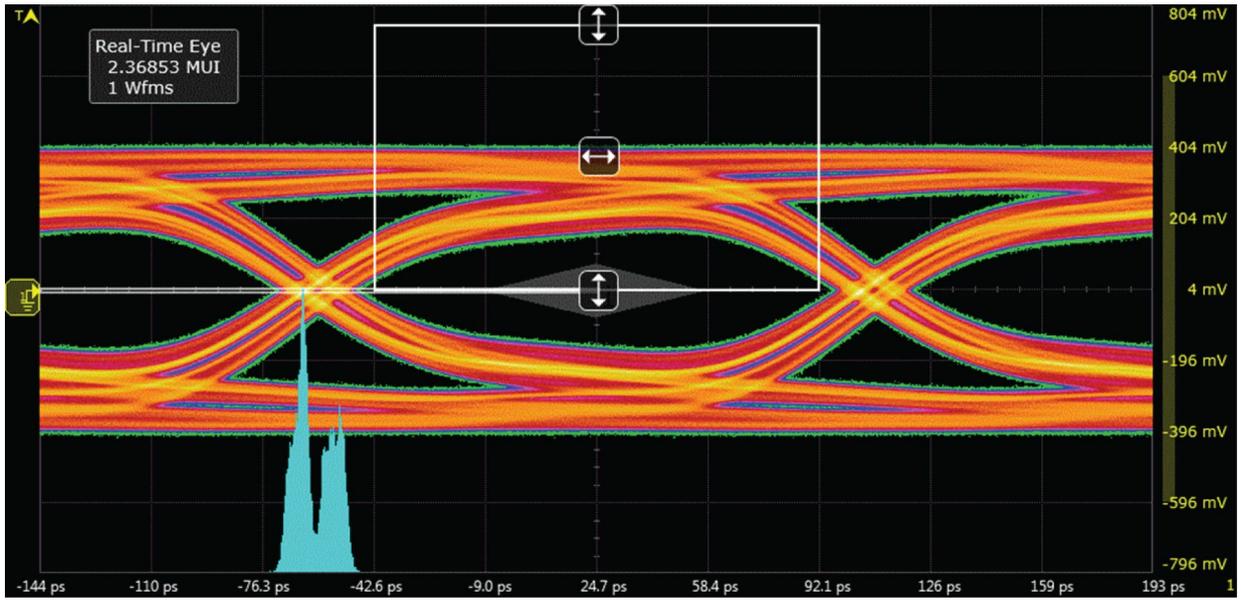


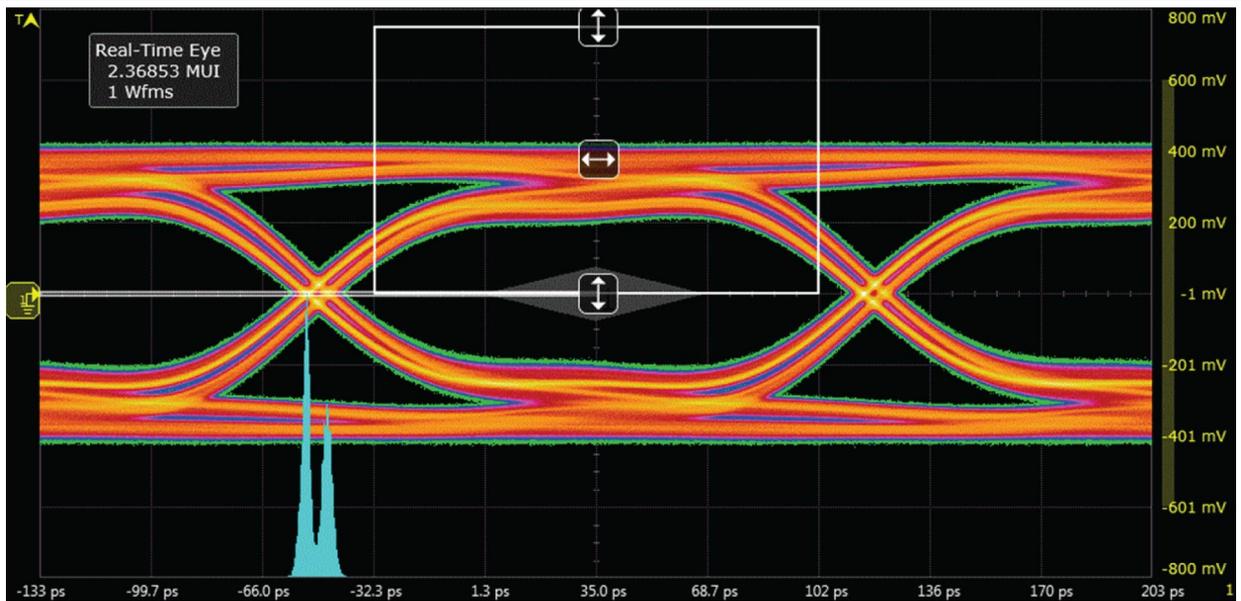
Fig. 8. USB 3.2 eye diagram 5 Gbps, test board without device; typical values

Common-mode EMI filter for differential channels with integrated bidirectional ESD protection



1080p, 6 Gbps

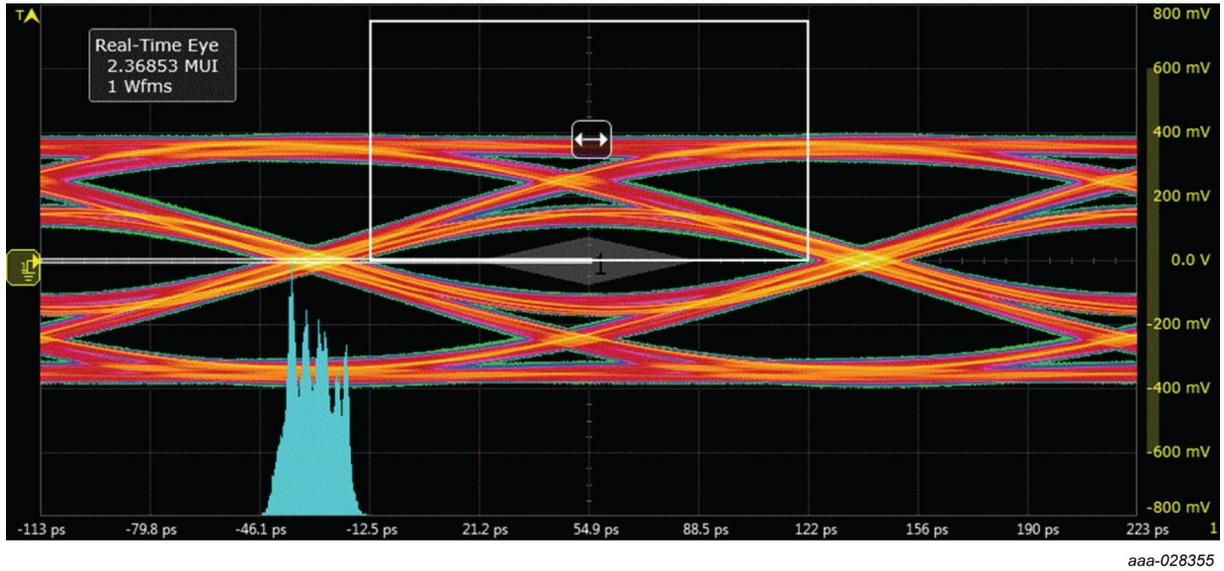
Fig. 9. HDMI 2.0 eye diagram TP1, test board with PCMFxUSB3B/C; typical values



1080p, 6 Gbps

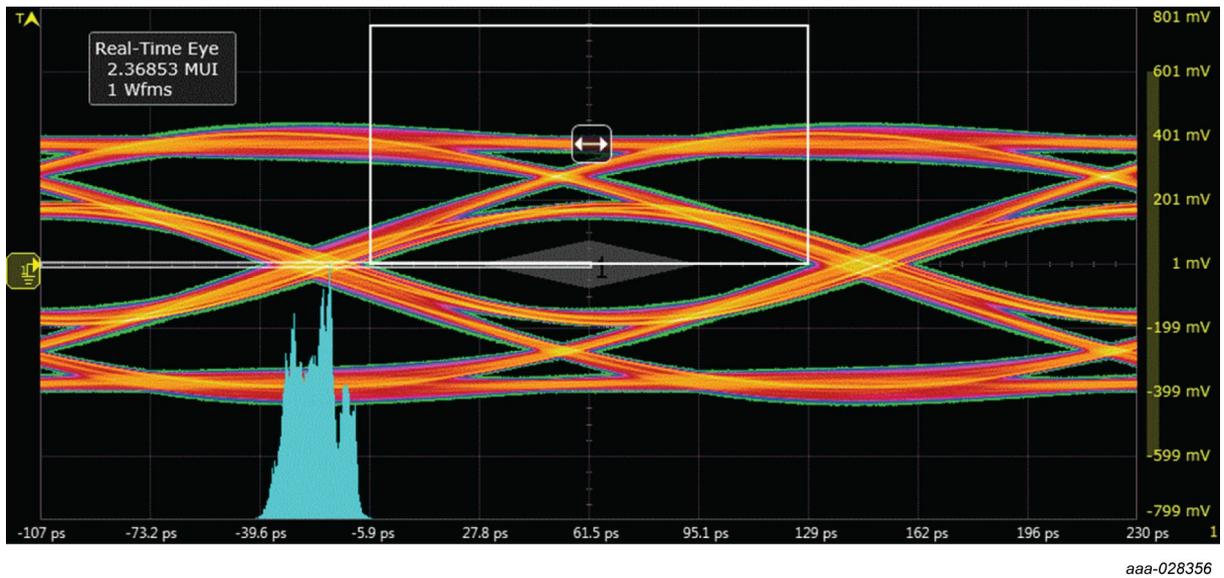
Fig. 10. HDMI 2.0 eye diagram TP1, test board without device; typical values

Common-mode EMI filter for differential channels with integrated bidirectional ESD protection



1080p, 6 Gbps

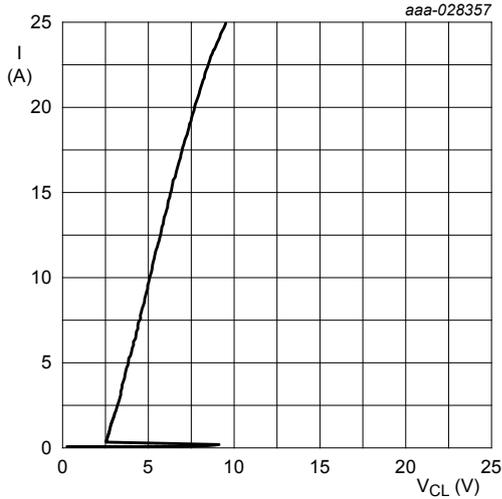
Fig. 11. HDMI 2.0 eye diagram TP2, test board with PCMFxUSB3B/C; typical values



1080p, 6 Gbps

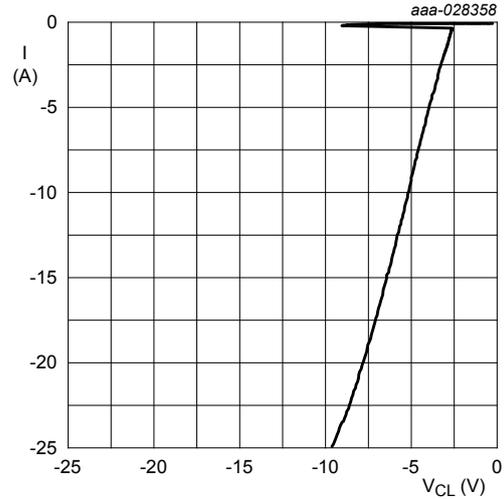
Fig. 12. HDMI 2.0 eye diagram TP2, test board without device; typical values

Common-mode EMI filter for differential channels with integrated bidirectional ESD protection



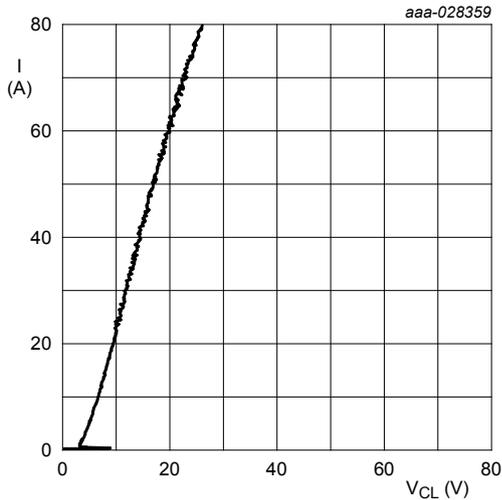
Transmission Line Pulse (TLP) = 100 ns;  
measured CH\_IN to GND

**Fig. 13. Dynamic resistance with positive clamping; typical values**



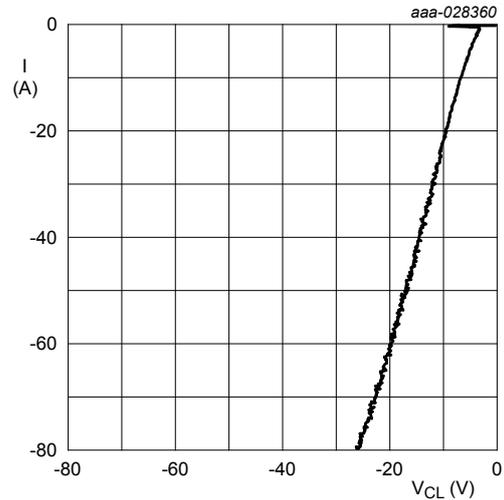
Transmission Line Pulse (TLP) = 100 ns;  
measured CH\_IN to GND

**Fig. 14. Dynamic resistance with negative clamping; typical values**



Very-Fast Transmission Line Pulse  
(VF-TLP) = 5 ns;  
measured CH\_IN to GND

**Fig. 15. Dynamic resistance with positive clamping; typical values**

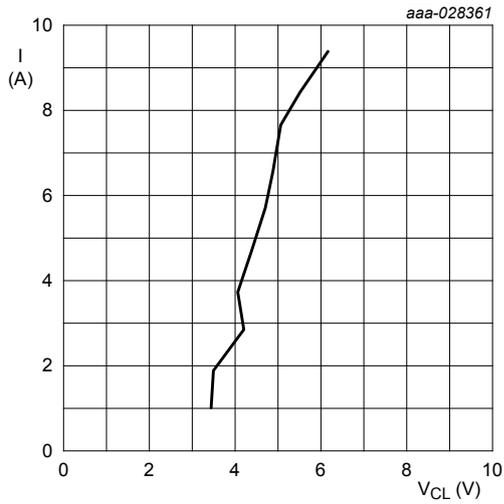


Very-Fast Transmission Line Pulse  
(VF-TLP) = 5 ns;  
measured CH\_IN to GND

**Fig. 16. Dynamic resistance with negative clamping; typical values**

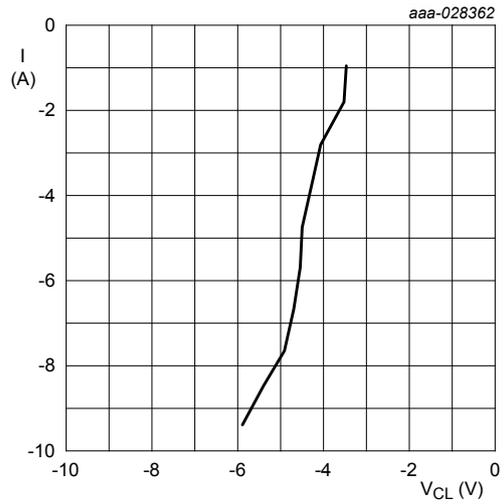
The device uses an advanced clamping structure showing a negative dynamic resistance. This snap-back behavior strongly reduces the clamping voltage to the system behind the ESD protection during an ESD event. Do not connect unlimited DC current sources to the data lines to avoid keeping the ESD protection device in snap-back state after exceeding breakdown voltage (due to an ESD pulse for instance).

Common-mode EMI filter for differential channels with integrated bidirectional ESD protection



IEC61000-4-5;  $t_p = 8/20 \mu s$ ; positive pulse

**Fig. 17. Dynamic resistance with positive clamping; typical values**



IEC61000-4-5;  $t_p = 8/20 \mu s$ ; negative pulse

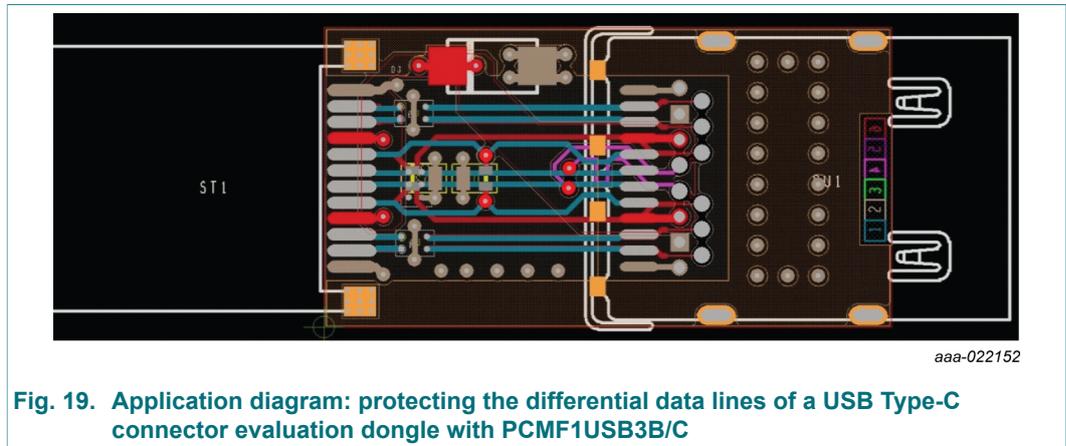
**Fig. 18. Dynamic resistance with negative clamping; typical values**

## 9. Application information

The device is designed to provide high-level ESD protection for differential high-speed data line pairs such as:

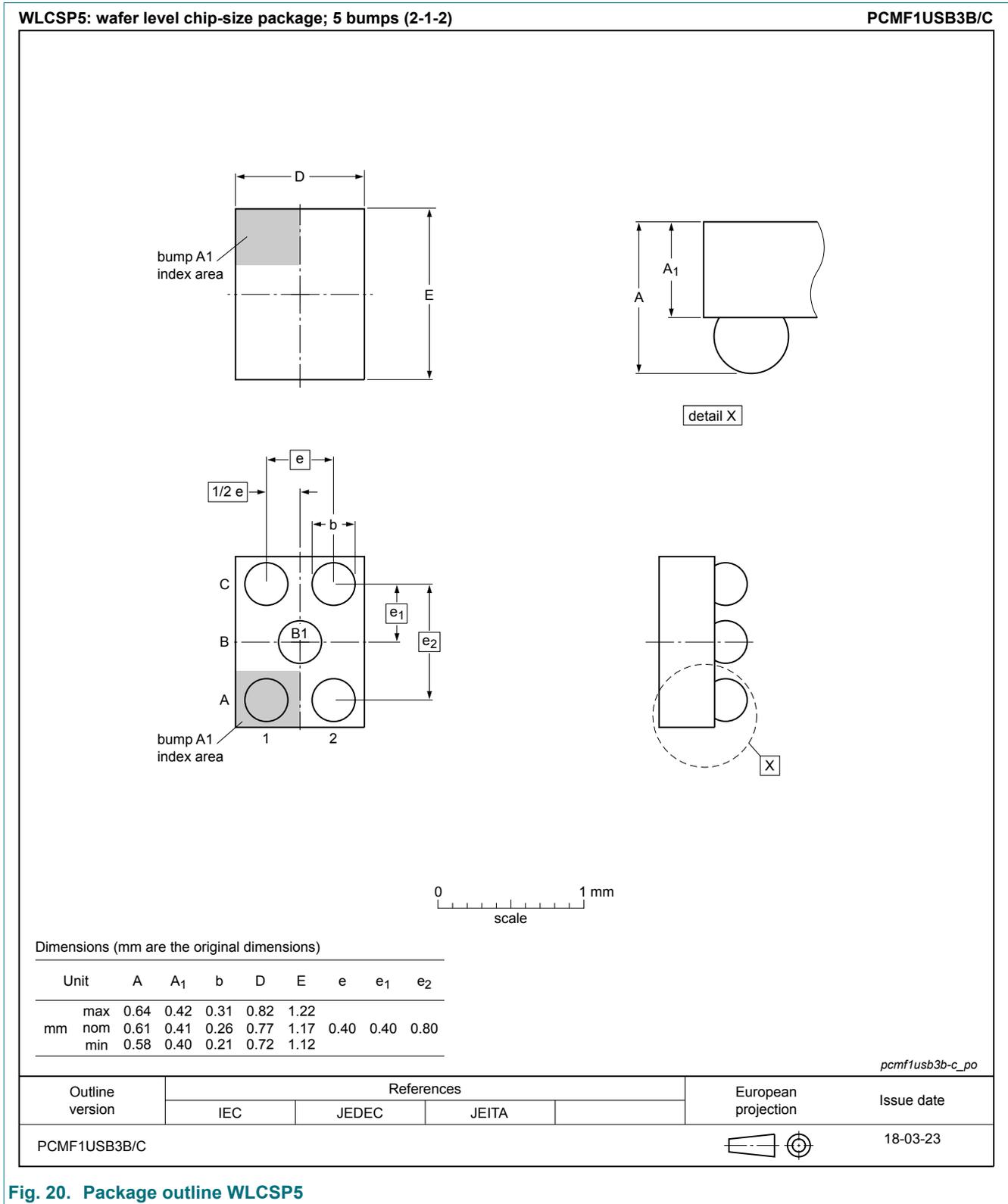
- USB 3.2
- HDMI 2.0
- Transition-Minimized Differential Signaling (TMDS)
- DisplayPort
- external Serial Advanced Technology Attachment (eSATA)
- Low Voltage Differential Signaling (LVDS)

When designing the Printed-Circuit Board (PCB), give careful consideration to impedance matching and signal coupling. Do not connect the protected signal lines to unlimited current sources like, for example, a battery.

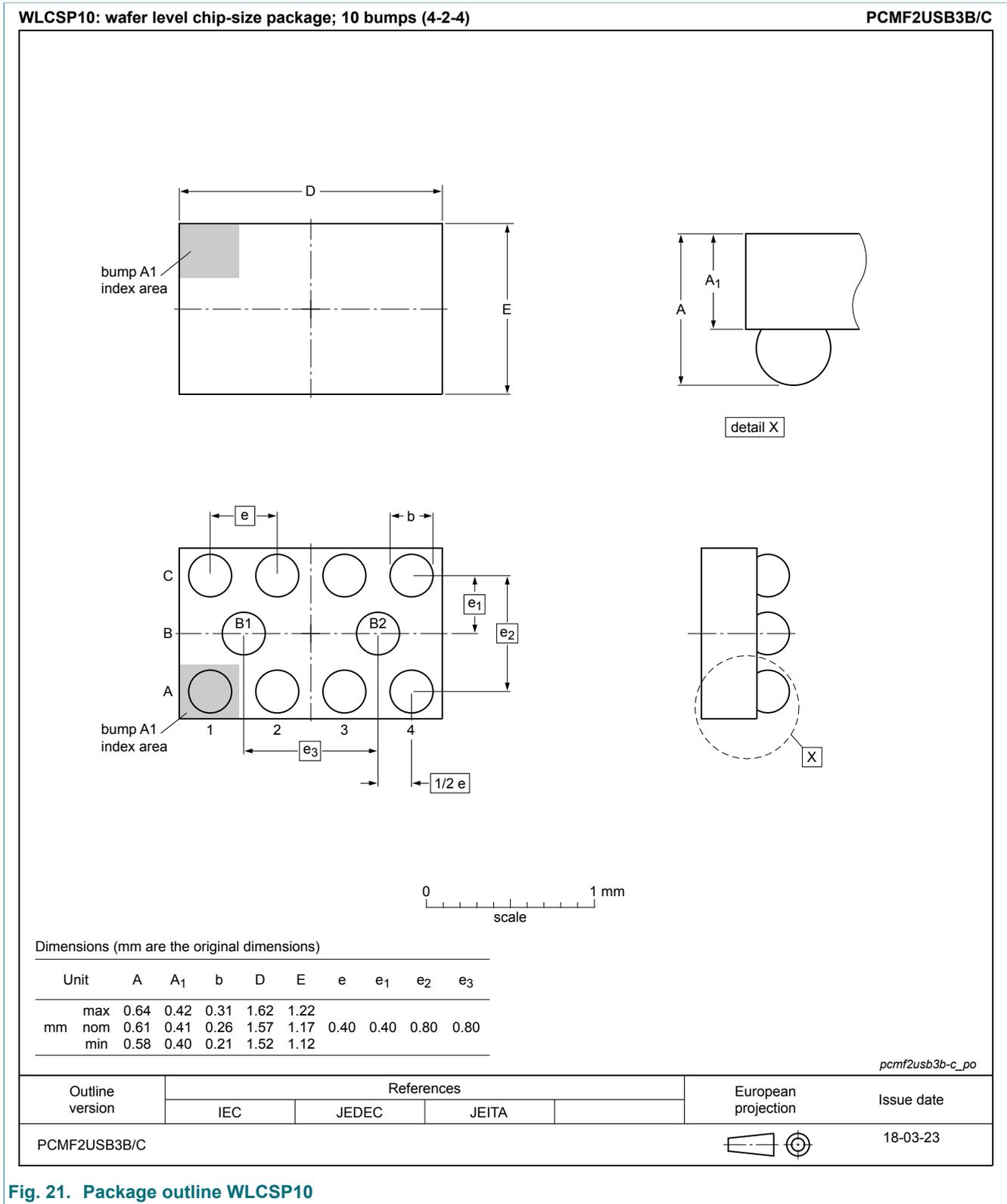


Since the SuperSpeed TX/RX lines are separated by GND or VBUS from the Hi-Speed lines, PCMF1USB3B/C makes it easy to achieve same signal lengths, straight routing, and optimal positioning for ESD protection directly at the connector.

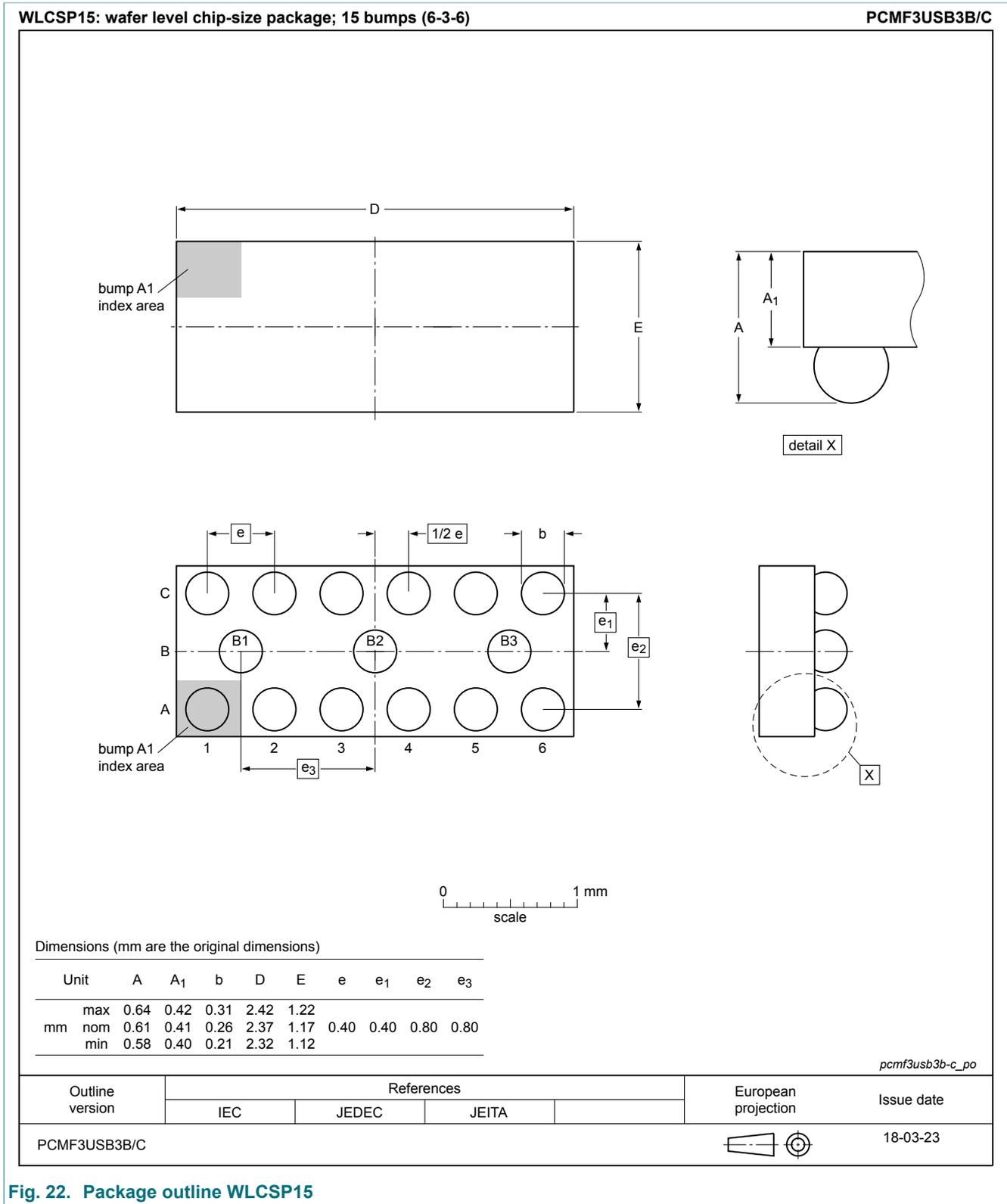
### 10. Package outline



**Fig. 20. Package outline WLCSP5**



**Fig. 21. Package outline WLCSP10**



**Fig. 22. Package outline WLCSP15**

### 11. Soldering

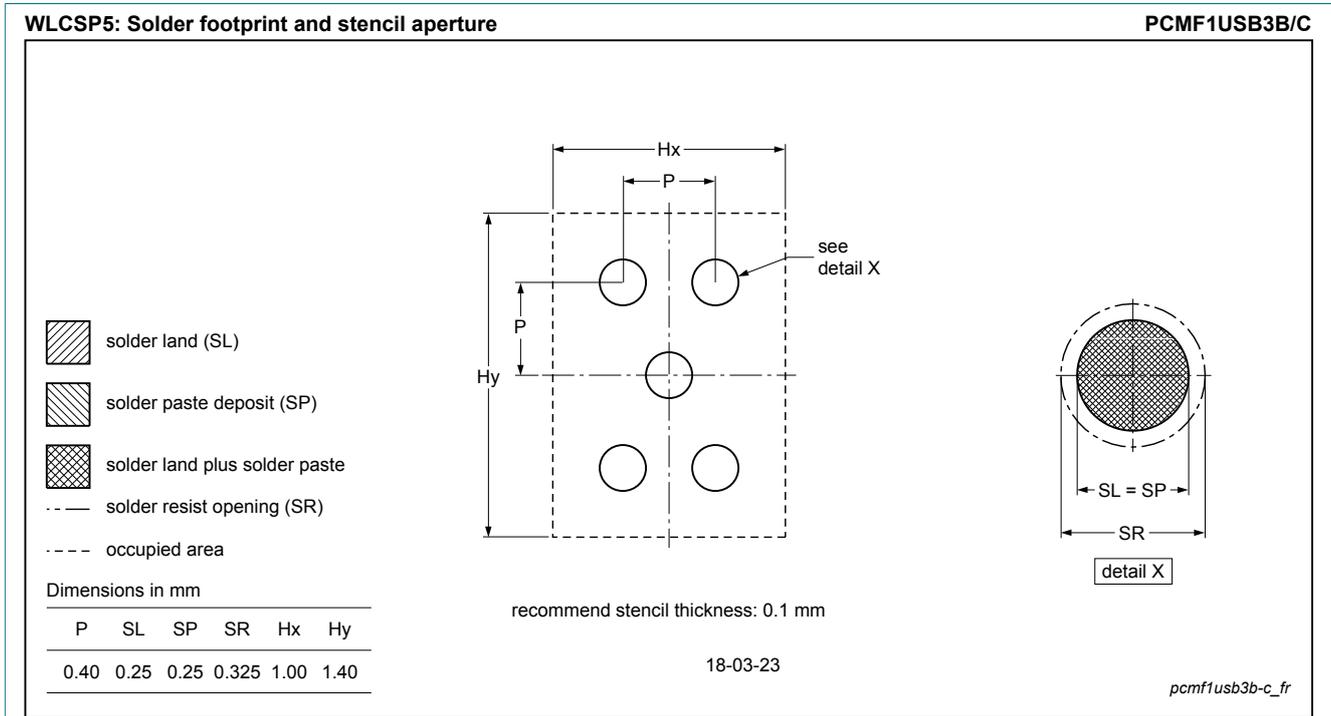


Fig. 23. Soldering footprint WLCSP5 (PCMF1USB3B/C)

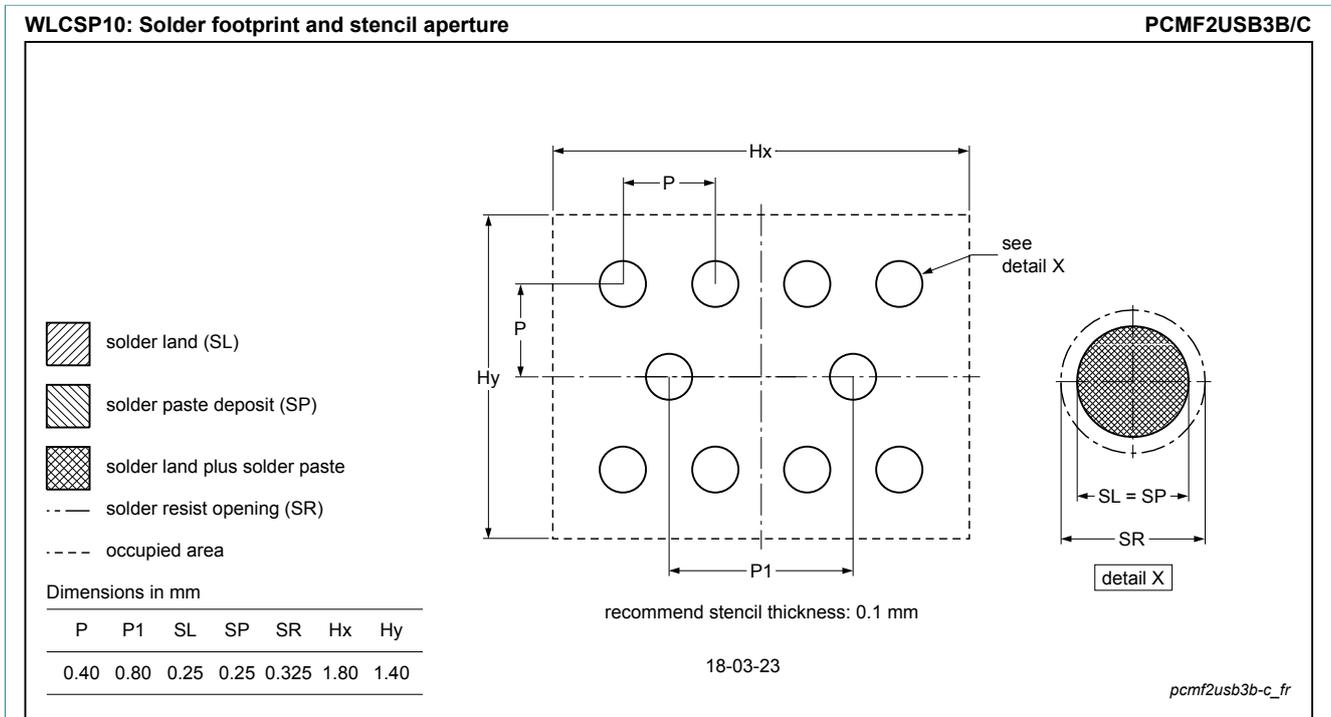
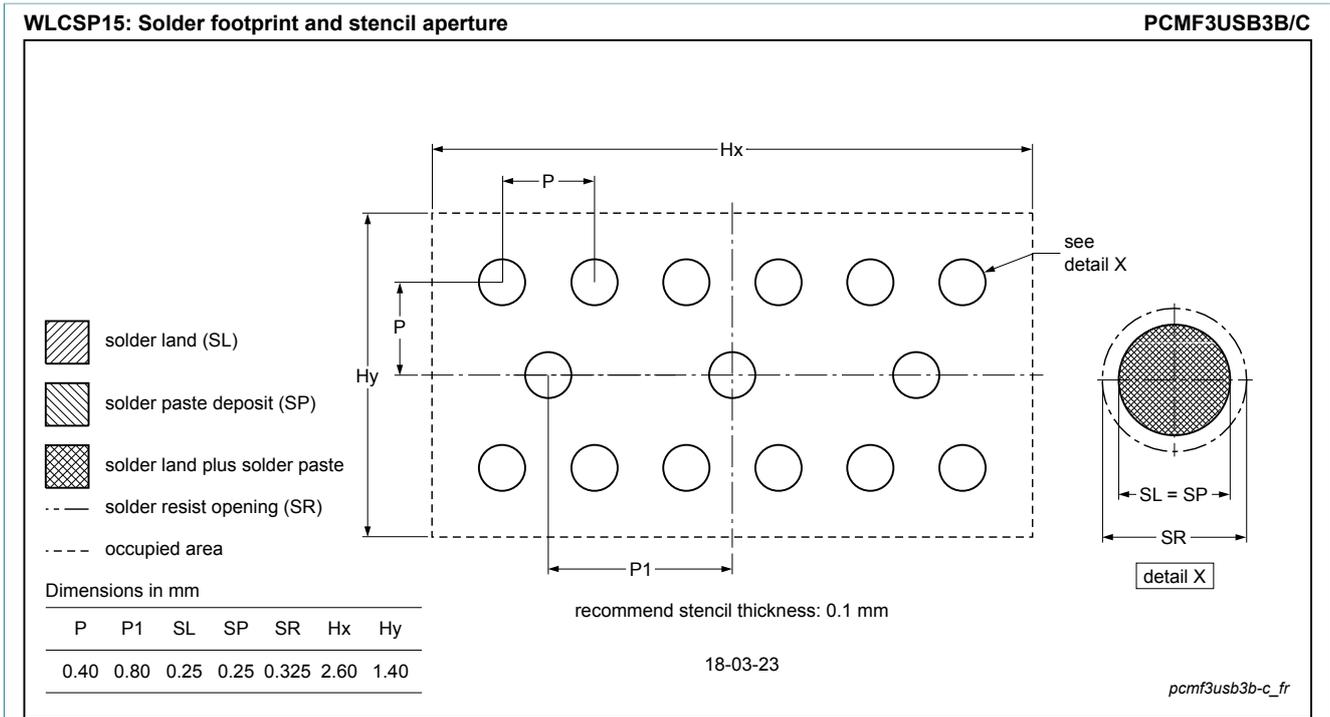


Fig. 24. Soldering footprint WLCSP10 (PCMF2USB3B/C)



**Fig. 25. Soldering footprint WLCSP15 (PCMF3USB3B/C)**

## 12. Revision history

Table 8. Revision history

| Document ID          | Release date   | Data sheet status  | Change notice | Supersedes           |
|----------------------|--|--------------------|---------------|----------------------|
| PCMFxUSB3B_C_SER v.2 | 20190129   | Product data sheet | -             | PCMFxUSB3B_C_SER v.1 |
| Modifications:       | <ul style="list-style-type: none"><li>Limiting values: <math>T_{amb}</math> updated.</li><li>Channel characteristics: Sentence inserted; <math>R_{S(ch)}</math> inserted.</li><li>Frequency characteristics: Sentence inserted; Fig 2 updated.</li></ul> |                    |               |                      |
| PCMFxUSB3B_C_SER v.1 | 20180507   | Product data sheet | -             | -                    |

## 13. Legal information

### Data sheet status

| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification      | This document contains data from the preliminary specification.                       |
| Product [short] data sheet     | Production         | This document contains the product specification.                                     |

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 29 January 2019

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